



**TOREX Semiconductor Ltd.**  
Sakura Ninonbashi Bldg. 8F  
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Chuo-Ku, Tokyo 103-0025  
Japan  
Phone: +81-3-5652-8725  
FAX: +81-3-5652-8731  
<http://www.torex.co.jp>

Dear Customer,

**Re: Environmental Declaration for TOREX's products**

We hereby declare that our products produced under our environmental management system certified by **ISO14001 (Certificate No. JQA-EMS3035)**. We are also implementing green procurement based primarily on the requirements of **SONY's Green Partner (Certificate No.S0202)**, and any substances banned under its standard SS-00259 including six substances referred under **EU RoHS Directive 2002/95/EC** and **ACPEIP:电子信息产品污染控制管理办法 (2006)** listed below are not intentionally used in the products (except for exempted applications by the directive); otherwise, the content levels of such substances as impurity do not exceed the limits specified by these standards.

- ◇ Cadmium
- ◇ Lead
- ◇ Mercury
- ◇ Chromium VI
- ◇ PBB
- ◇ PBDE

If any circumstances occurred due to a violation against the non-use statement above, we will sincerely reach a negotiated settlement with our customers, who have a direct contract with TOREX Semiconductor Ltd., for the damage.

\*Attached are the Analysis results data.

Takara Yoshida  
General Manager, Quality Assurance Dept.

To: BYD COMPANY LIMITED.

TOREX No. T08-E-70603

2008/3/26

TOREX Semiconductor Device HK Ltd.  
TOREX Semiconductor Ltd.

## Composition Table

Product(Pb-free): XC6219BxxxMR  
Typical Mass: 15 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
IC chip	0.666	Silicon	44400	7440-21-3
	-	Arsenic	2	7440-38-2
Leadframe	5.503	Copper	366800	7440-50-8
	0.022	Tin	1500	7440-31-5
	0.021	Zinc	1400	7440-66-6
	0.024	Chromium	1600	7440-47-3
	0.325	Silver	21700	7440-22-4
Die attach adhesive	0.009	Epoxy	600	-
	0.049	Silver	3200	7440-22-4
Bonding wire	0.050	Gold	3300	7440-57-5
Molding compound	6.062	Silica	404100	60676-86-0
	0.973	Epoxy resin	64900	-
	0.507	Phenol resin	33800	-
	0.118	Antimony trioxide	7900	1309-64-4
	0.285	Brominated resin	19000	-
	0.047	Organic phosphorus	3200	-
Plating (1)	0.007	Bismuth	500	7440-69-9
	0.333	Tin	22200	7440-31-5
Plating (2)	0.340	Tin	22700	7440-31-5
Plating (3)	0.012	Silver	800	7440-22-4
	0.328	Tin	21900	7440-31-5

\*The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\*Any indication "-" in CAS number means "confidential."

\*If more than one termination plating types are listed, the composition is either (1), (2), or (3).



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TOREX SEMICONDUCTOR LTD.

SAKURANIHONBASHI BLDG. 8F, 1-13-12, NIHONBASHI KAYABACHO,  
CHUO-KU, TOKYO 103-0025, JAPAN



The following sample(s) was/were submitted and identified by/on behalf of the client as :

Sample Description : IC  
 Style/Item No. : SOT-25  
 Sample Receiving Date : 2008/01/29  
 Testing Period : 2008/01/29 TO 2008/02/05

Test Requested : In accordance with the RoHS Directive 2002/95/EC, and its amendment directives.

Test Method : With reference to IEC 62321, Ed.1 111/54/CDV  
 Procedures for the Determination of Levels of Regulated  
 Substances in Electrotechnical Products.

- (1) Determination of Cadmium by ICP-AES.
- (2) Determination of Lead by ICP-AES.
- (3) Determination of Mercury by ICP-AES.
- (4) Determination of Hexavalent Chromium for non-metallic samples by UV/Vis Spectrometry.
- (5) Determination of PBB and PBDE by GC/MS.

Test Result(s) : Please refer to next page(s).

**Chenyu Kung / Operation Manager**  
**Signed for and on behalf of**  
**SGS TAIWAN LTD.**  
**Chemical Laboratory – Taipei**

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SAKURANIHONBASHI BLDG. 8F, 1-13-12, NIHONBASHI KAYABACHO,  
CHUO-KU, TOKYO 103-0025, JAPAN



Test results by chemical method (Unit: mg/kg)

Test Item (s):	Method (Refer to)	Result	MDL
		No.1	
Cadmium (Cd)	(1)	n.d.	2
Lead (Pb)	(2)	n.d.	2
Mercury (Hg)	(3)	n.d.	2
Hexavalent Chromium Cr(VI) by alkaline extraction	(4)	n.d.	2
<b>Sum of PBBs</b>	(5)	n.d.	-
Monobromobiphenyl		n.d.	5
Dibromobiphenyl		n.d.	5
Tribromobiphenyl		n.d.	5
Tetrabromobiphenyl		n.d.	5
Pentabromobiphenyl		n.d.	5
Hexabromobiphenyl		n.d.	5
Heptabromobiphenyl		n.d.	5
Octabromobiphenyl		n.d.	5
Nonabromobiphenyl		n.d.	5
Decabromobiphenyl		n.d.	5
<b>Sum of PBDEs (Mono to Nona) (Note 4)</b>		n.d.	-
Monobromobiphenyl ether		n.d.	5
Dibromobiphenyl ether		n.d.	5
Tribromobiphenyl ether		n.d.	5
Tetrabromobiphenyl ether		n.d.	5
Pentabromobiphenyl ether		n.d.	5
Hexabromobiphenyl ether		n.d.	5
Heptabromobiphenyl ether		n.d.	5
Octabromobiphenyl ether		n.d.	5
Nonabromobiphenyl ether		n.d.	5
Decabromobiphenyl ether		n.d.	5
<b>Sum of PBDEs (Mono to Deca)</b>		n.d.	-

### TEST PART DESCRIPTION:

NO.1 : MIXED ALL PARTS

Note : 1. mg/kg = ppm

2. n.d. = Not Detected

3. MDL = Method Detection Limit

4. According to 2005/717/EC DecaBDE is exempt.

5. "-" = Not Regulated

6. The sample(s) was/were analyzed on behalf of the applicant as mixing sample in one testing.

The above result(s) was/were only given as the informality value.

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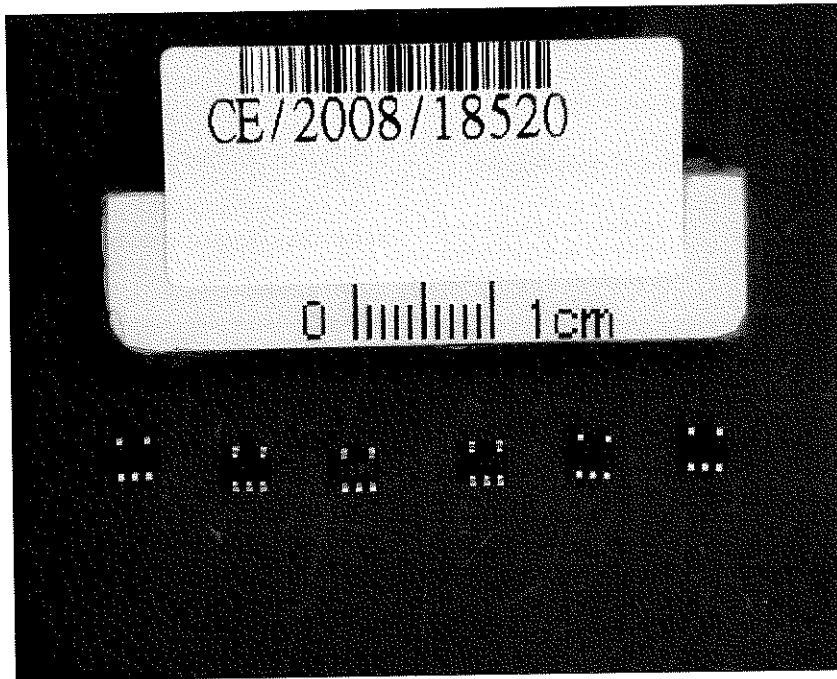
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\*\* End of Report \*\*

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